

# Hisashi Yamada

## List of Publications by Year in descending order

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96  
papers

1,705  
citations

257450

24  
h-index

345221

36  
g-index

97  
all docs

97  
docs citations

97  
times ranked

1379  
citing authors

#	ARTICLE	IF	CITATIONS
1	Comparative Study of Boron Precursors for Chemical Vapor-Phase Deposition-Grown Hexagonal Boron Nitride Thin Films. <i>Physica Status Solidi (A) Applications and Materials Science</i> , 2021, 218, 2000241.	1.8	8
2	Dielectric functions of CVD-grown boron nitride from 1.1 to 9.0 eV by spectroscopic ellipsometry. <i>Applied Physics Letters</i> , 2021, 118, 112101.	3.3	6
3	Impact of gate electrode formation process on Al <sub>2</sub> O <sub>3</sub> /GaN interface properties and channel mobility. <i>Applied Physics Express</i> , 2021, 14, 081001.	2.4	4
4	Generation of dislocations from scratches on GaN formed during wafer fabrication and dislocation reactions during homoepitaxial growth. <i>Japanese Journal of Applied Physics</i> , 2021, 60, 115501.	1.5	5
5	Fabrication and analysis of InAlN/GaN metal-insulator-semiconductor high-electron-mobility transistors based on AlN/GaN superlattice channel. <i>Applied Physics Letters</i> , 2021, 119, .	3.3	2
6	Analysis of dislocation line tilt in GaN single crystal by Raman spectroscopy. <i>Japanese Journal of Applied Physics</i> , 2021, 60, SAAD03.	1.5	1
7	Chemical Vapor Deposition Growth of BN Thin Films Using B <sub>2</sub> H <sub>6</sub> and NH <sub>3</sub> . <i>Physica Status Solidi (B): Basic Research</i> , 2020, 257, 1900318.	1.5	11
8	Experimental Demonstration of n- and p-channel GaN-MOSFETs toward Power IC Applications. <i>ECS Journal of Solid State Science and Technology</i> , 2020, 9, 015001.	1.8	7
9	Growth Temperature Effects of Chemical Vapor Deposition-Grown Boron Nitride Layer Using B <sub>2</sub> H <sub>6</sub> and NH <sub>3</sub> . <i>Physica Status Solidi (B): Basic Research</i> , 2020, 257, 1900521.	1.5	4
10	Ferroelectrics field modulation imaging: A useful technique for domain and domain-wall observations. <i>Ferroelectrics</i> , 2020, 556, 37-43.	0.6	2
11	Fabrication and Evaluation of N-Channel GaN Metal-Oxide-Semiconductor Field-Effect Transistors Based on Regrown and Implantation Methods. <i>Materials</i> , 2020, 13, 899.	2.9	9
12	Behavior of Threading Dislocations from GaN Substrate to Epitaxial Layer. <i>Physica Status Solidi (B): Basic Research</i> , 2020, 257, 1900527.	1.5	4
13	Impact of remote plasma oxidation of a GaN surface on photoluminescence properties. <i>Japanese Journal of Applied Physics</i> , 2019, 58, SEEC02.	1.5	2
14	Comparative study of photoluminescence properties obtained from SiO <sub>2</sub> /GaN and Al <sub>2</sub> O <sub>3</sub> /GaN structures. <i>Japanese Journal of Applied Physics</i> , 2019, 58, SIIB22.	1.5	0
15	Controlled oxide interlayer for improving reliability of SiO <sub>2</sub> /GaN MOS devices. <i>Japanese Journal of Applied Physics</i> , 2019, 58, SCCD06.	1.5	22
16	Nondestructive visualization of threading dislocations in GaN by micro raman mapping. <i>Japanese Journal of Applied Physics</i> , 2019, 58, SCCB06.	1.5	12
17	Reduction in residual impurities in semi-polar $\text{Al}_x\text{Ga}_{1-x}\text{N}$ epilayers grown on GaN substrates by selective area growth. <i>Journal of Crystal Growth</i> , 2019, 507, 437-441.	1.5	0
18	Fabrication of submicron active-region-buried GaN hexagonal frustum structures by selective area growth for directional micro-LEDs. <i>Journal of Crystal Growth</i> , 2019, 507, 437-441.	1.5	3

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19	Impact of substrate off-angle on the <i>m</i> -plane GaN Schottky diodes. Japanese Journal of Applied Physics, 2018, 57, 04FG01.	1.5	14
20	Control of Ga-oxide interlayer growth and Ga diffusion in SiO <sub>2</sub> /GaN stacks for high-quality GaN-based metal-oxide semiconductor devices with improved gate dielectric reliability. Applied Physics Express, 2018, 11, 015701.	2.4	35
21	High thermal stability of abrupt SiO <sub>2</sub> /GaN interface with low interface state density. Japanese Journal of Applied Physics, 2018, 57, 04FG11.	1.5	14
22	Comparison of Electrical Properties of Ni/n-GaN Schottky Diodes on <i>c</i> -plane and <i>m</i> -plane GaN Substrates. Physica Status Solidi (A) Applications and Materials Science, 2018, 215, 1700362.	1.8	9
23	Energy band structure and electrical properties of Ga-oxide/GaN interface formed by remote oxygen plasma. Japanese Journal of Applied Physics, 2018, 57, 06KA05.	1.5	5
24	Determination of edge-component Burgers vector of threading dislocations in GaN crystal by using Raman mapping. Applied Physics Express, 2018, 11, 111001.	2.4	11
25	Carrier conduction in SiO <sub>2</sub> /GaN structure with abrupt interface. , 2018, , .		0
26	Low-temperature formation of Ga-oxide/GaN interface with remote oxygen plasma and its interface properties. Japanese Journal of Applied Physics, 2018, 57, 06JE01.	1.5	3
27	Detection of edge component of threading dislocations in GaN by Raman spectroscopy. Applied Physics Express, 2018, 11, 061002.	2.4	13
28	Interface properties of SiO <sub>2</sub> /GaN structures formed by chemical vapor deposition with remote oxygen plasma mixed with Ar or He. Japanese Journal of Applied Physics, 2018, 57, 06KA01.	1.5	3
29	Deep-level traps in lightly Si-doped <i>n</i> -GaN on free-standing <i>m</i> -oriented GaN substrates. AIP Advances, 2018, 8, .	1.3	12
30	Electrical properties of Ni/n-GaN Schottky diodes on freestanding <i>m</i> -plane GaN substrates. Applied Physics Express, 2017, 10, 041001.	2.4	15
31	Formation and reduction of pyramidal hillocks on InGaAs/InP(111)A. Physica Status Solidi (B): Basic Research, 2016, 253, 644-647.	1.5	0
32	Impact of La <sub>2</sub> O <sub>3</sub> interfacial layers on InGaAs metal-oxide-semiconductor interface properties in Al <sub>2</sub> O <sub>3</sub> /La <sub>2</sub> O <sub>3</sub> /InGaAs gate stacks deposited by atomic-layer-deposition. Journal of Applied Physics, 2015, 118, .	2.5	17
33	High mobility CMOS technologies using III-V/Ge channels on Si platform. Solid-State Electronics, 2013, 88, 2-8.	1.4	64
34	Experimental Study on Electron Mobility in In <sub>x</sub> Ga <sub>1-x</sub> As-on-Insulator Metal-Oxide-Semiconductor Field-Effect Transistors With In Content Modulation and MOS Interface Buffer Engineering. IEEE Nanotechnology Magazine, 2013, 12, 621-628.	2.0	28
35	Enhancement mechanism of terahertz radiation from coherent longitudinal optical phonons in undoped GaAs/ <i>n</i> -type GaAs epitaxial structures. Journal of Applied Physics, 2013, 113, .	2.5	21
36	Characteristics of ultrafast optical responses originating from non-equilibrium carrier transport in undoped GaAs/ <i>n</i> -type GaAs epitaxial structures. Journal of Applied Physics, 2013, 113, .	2.5	6

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37	Formation of III-V-on-insulator structures on Si by direct wafer bonding. Semiconductor Science and Technology, 2013, 28, 094009.	2.0	47
38	III-V/Ge High Mobility Channel Integration of InGaAs n-Channel and Ge p-Channel Metal-Oxide-Semiconductor Field-Effect Transistors with Self-Aligned Ni-Based Metal Source/Drain Using Direct Wafer Bonding. Applied Physics Express, 2012, 5, 076501.	2.4	26
39	Electron Mobility Enhancement of Extremely Thin Body In <sub>0.7</sub> Ga <sub>0.3</sub> As-on-Insulator Metal-Oxide-Semiconductor Field-Effect Transistors on Si Substrates by Metal-Oxide-Semiconductor Interface Buffer Layers. Applied Physics Express, 2012, 5, 014201.	2.4	26
40	Controlling Anion Composition at Metal-Insulator-Semiconductor Interfaces on III-V Channels by Plasma Processing. Japanese Journal of Applied Physics, 2012, 51, 065701.	1.5	2
41	Ultrafast optical response originating from carrier-transport processes in undoped GaAs/n-type GaAs epitaxial structures. Applied Physics Letters, 2012, 100, 211902.	3.3	5
42	Sulfur cleaning for (100), (111)A, and (111)B InGaAs surfaces with In content of 0.53 and 0.70 and their Al <sub>2</sub> O <sub>3</sub> /InGaAs MOS interface properties. , 2012, , .		4
43	Time Evolution of Terahertz Electromagnetic Waves from Undoped GaAs/n-type GaAs Epitaxial Layer Structures Clarified with Use of a Time-Partitioning Fourier Transform Method. Physics Procedia, 2012, 29, 30-35.	1.2	0
44	Reduction in interface state density of Al <sub>2</sub> O <sub>3</sub> /InGaAs metal-oxide-semiconductor interfaces by InGaAs surface nitridation. Journal of Applied Physics, 2012, 112, 073702.	2.5	41
45	Initial Processes of Atomic Layer Deposition of Al <sub>2</sub> O <sub>3</sub> on InGaAs: Interface Formation Mechanisms and Impact on Metal-Insulator-Semiconductor Device Performance. Materials, 2012, 5, 404-414.	2.9	18
46	Controlling Anion Composition at Metal-Insulator-Semiconductor Interfaces on III-V Channels by Plasma Processing. Japanese Journal of Applied Physics, 2012, 51, 065701.	1.5	2
47	Sub-10-nm Extremely Thin Body InGaAs-on-Insulator MOSFETs on Si Wafers With Ultrathin $\text{Al}_2\text{O}_3$ Buried Oxide Layers. IEEE Electron Device Letters, 2011, 32, 1218-1220.	3.9	60
48	Origin of electron mobility enhancement in (1 1 1)-oriented InGaAs channel metal-insulator-semiconductor field-effect-transistors. Microelectronic Engineering, 2011, 88, 3459-3461.	2.4	9
49	Simple strategy for enhancing terahertz emission from coherent longitudinal optical phonons using undoped GaAs/n-type GaAs epitaxial layer structures. Physica Status Solidi C: Current Topics in Solid State Physics, 2011, 8, 343-345.	0.8	2
50	On the mechanisms limiting mobility in InP/InGaAs buried channel nMISFETs. Microelectronic Engineering, 2011, 88, 1076-1078.	2.4	2
51	AC response analysis of C-V curves and quantitative analysis of conductance curves in Al <sub>2</sub> O <sub>3</sub> /InP interfaces. Microelectronic Engineering, 2011, 88, 1087-1090.	2.4	16
52	Frequency-tunable terahertz electromagnetic wave emitters based on undoped GaAs/n-type GaAs epitaxial layer structures utilizing sub-picosecond-range carrier-transport processes. Journal of Luminescence, 2011, 131, 531-534.	3.1	0
53	Self-aligned metal source/drain InP n-metal-oxide-semiconductor field-effect transistors using Ni-InP metallic alloy. Applied Physics Letters, 2011, 98, 243501.	3.3	21
54	High Performance Extremely Thin Body InGaAs-on-Insulator Metal-Oxide-Semiconductor Field-Effect Transistors on Si Substrates with Ni-InGaAs Metal Source/Drain. Applied Physics Express, 2011, 4, 114201.	2.4	28

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55	Self-Aligned Metal Source/Drain In <sub>x</sub> Ga <sub>1-x</sub> As n-Metalâ€“Oxideâ€“Semiconductor Field-Effect Transistors Using Niâ€“InGaAs Alloy. Applied Physics Express, 2011, 4, 024201.	2.4	53
56	Ultrathin Body InGaAs-on-Insulator Metalâ€“Oxideâ€“Semiconductor Field-Effect Transistors with InP Passivation Layers on Si Substrates Fabricated by Direct Wafer Bonding. Applied Physics Express, 2011, 4, 054202.	2.4	20
57	(Invited) III-V-On-Insulator MOSFETs on Si Substrates Fabricated by Direct Bonding Technique. ECS Transactions, 2010, 33, 359-370.	0.5	1
58	Self-aligned metal source/drain In <sub>x</sub> Ga <sub>1-x</sub> As n-MOSFETs using Ni-InGaAs alloy. , 2010, , .		15
59	Correlation between channel mobility improvements and negative V <sub>th</sub> shifts in III&#x2013;V MISFETs: Dipole fluctuation as new scattering mechanism. , 2010, , .		10
60	Impact of InGaAs surface nitridation on interface properties of InGaAs metal-oxide-semiconductor capacitors using electron cyclotron resonance plasma sputtering SiO <sub>2</sub> . Applied Physics Letters, 2010, 97, 132102.	3.3	29
61	Front-gate InGaAs-on-Insulator metal-insulator-semiconductor field-effect transistors. Applied Physics Letters, 2010, 97, 253502.	3.3	18
62	Extremely-thin-body InGaAs-on-insulator MOSFETs on Si fabricated by direct wafer bonding. , 2010, , .		33
63	High Quality Thin Body III-V-On-Insulator Channel Layer Transfer on Si Wafer Using Direct Wafer Bonding. ECS Transactions, 2010, 33, 391-401.	0.5	8
64	Frequency Shift of Terahertz Electromagnetic Waves Originating from Sub-Picosecond-Range Carrier Transport in Undoped GaAs/n-Type GaAs Epitaxial Layer Structures. Japanese Journal of Applied Physics, 2010, 49, 082001.	1.5	5
65	III-V-semiconductor-on-insulator n-channel metal-insulator-semiconductor field-effect transistors with buried Al <sub>2</sub> O <sub>3</sub> layers and sulfur passivation: Reduction in carrier scattering at the bottom interface. Applied Physics Letters, 2010, 96, 142106.	3.3	64
66	High mobility III&#x2013;V-on-insulator MOSFETs on Si with ALD-Al <sub>2</sub> O <sub>3</sub> BOX layers. , 2010, , .		3
67	III-V-semiconductor-on-insulator MISFETs on Si with buried SiO <sub>2</sub> and Al <sub>2</sub> O <sub>3</sub> layers by direct wafer bonding. , 2010, , .		2
68	Evaluation of GaN substrates grown in supercritical basic ammonia. Applied Physics Letters, 2009, 94, 052109.	3.3	5
69	Relationships between Interface Structures and Electrical Properties in the High-k/IIIâ€“V System. Materials Research Society Symposia Proceedings, 2009, 1194, 68.	0.1	2
70	Customized Filter Cube in Fluorescence Microscope Measurements of InGaN/GaN Quantum-Well Characterization. Japanese Journal of Applied Physics, 2009, 48, 098003.	1.5	1
71	Effects of piezoelectric fields on optoelectronic properties of InGaN/GaN quantum-well light-emitting diodes prepared on nonpolar (1â€“0â€“0) and semipolar (1â€“1â€“2) orientations. Journal of Applied Physics, 2009, 42, 135106.		10
72	High Electron Mobility Metalâ€“Insulatorâ€“Semiconductor Field-Effect Transistors Fabricated on (111)-Oriented InGaAs Channels. Applied Physics Express, 2009, 2, 121101.	2.4	49

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73	Recent progress in nonpolar LEDs as polarized light emitters. <i>Physica Status Solidi (A) Applications and Materials Science</i> , 2009, 206, 203-205.	1.8	9
74	Thin Body III-V-Semiconductor-on-Insulator Metal-Oxide-Semiconductor Field-Effect Transistors on Si Fabricated Using Direct Wafer Bonding. <i>Applied Physics Express</i> , 2009, 2, 124501.	2.4	77
75	Optical polarization of $m$ -plane InGaN/GaN light-emitting diodes characterized via confocal microscope. <i>Physica Status Solidi (A) Applications and Materials Science</i> , 2008, 205, 1203-1206.	1.8	25
76	Effects of off-axis GaN substrates on optical properties of $m$ -plane InGaN/GaN light-emitting diodes. <i>Journal of Crystal Growth</i> , 2008, 310, 4968-4971.	1.5	25
77	Hydrogen-related defects in InGaP/GaAs heterojunction bipolar transistors. <i>Journal of Crystal Growth</i> , 2008, 310, 5223-5226.	1.5	1
78	Comparison of InGaN/GaN light emitting diodes grown on $m$ -plane and $a$ -plane bulk GaN substrates. <i>Physica Status Solidi - Rapid Research Letters</i> , 2008, 2, 89-91.	2.4	46
79	Optical polarization characteristics of $m$ -oriented InGaN/GaN light-emitting diodes with various indium compositions in single-quantum-well structure. <i>Journal Physics D: Applied Physics</i> , 2008, 41, 225104.	2.8	57
80	Non-polar-oriented InGaN light-emitting diodes for liquid crystal display backlighting. <i>Journal of the Society for Information Display</i> , 2008, 16, 571-578.	2.1	25
81	Optical polarization characteristics of InGaN-GaN light-emitting diodes fabricated on GaN substrates oriented between $(101\bar{A})$ and $(101\bar{A}1\bar{A})$ planes. <i>Applied Physics Letters</i> , 2008, 92, .	3.3	34
82	Impact of Substrate Miscut on the Characteristic of $m$ -plane InGaN/GaN Light Emitting Diodes. <i>Japanese Journal of Applied Physics</i> , 2007, 46, L1117-L1119.	1.5	52
83	Thin metal intracavity contact and lateral current-distribution scheme for GaN-based vertical-cavity lasers. <i>Applied Physics Letters</i> , 2007, 90, 181128.	3.3	9
84	High Brightness Blue InGaN/GaN Light Emitting Diode on Nonpolar $m$ -plane Bulk GaN Substrate. <i>Japanese Journal of Applied Physics</i> , 2007, 46, L960-L962.	1.5	89
85	Continuous-wave Operation of AlGaIn-cladding-free Nonpolar $m$ -Plane InGaN/GaN Laser Diodes. <i>Japanese Journal of Applied Physics</i> , 2007, 46, L761.	1.5	83
86	The Effect of $n$ -GaAs Carrier Concentration on Current Gain in InGaP/GaAs Heterojunction Bipolar Transistors. <i>Japanese Journal of Applied Physics</i> , 2007, 46, 5122-5124.	1.5	2
87	The optical excitation mechanism in ZnS: Sm <sup>3+</sup> grown by molecular-beam epitaxy. <i>Solid State Communications</i> , 2007, 142, 36-40.	1.9	7
88	Si-related defects in InGaP/GaAs heterojunction bipolar transistors. <i>Physica B: Condensed Matter</i> , 2007, 401-402, 44-47.	2.7	1
89	High current gain stability of carbon-doped $p$ -GaAs in InGaP/GaAs heterojunction bipolar transistors. <i>Journal of Crystal Growth</i> , 2007, 298, 857-860.	1.5	5
90	Influence of V/III Ratio of Carbon-Doped $p$ -GaAs on Current Gain and Its Thermal Stability in InGaP/GaAs Heterojunction Bipolar Transistors. <i>Japanese Journal of Applied Physics</i> , 2006, 45, 3909-3912.	1.5	8

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91	Well-width dependence of optical properties of rare-earth ion-doped ZnS <sub>0.8</sub> Se <sub>0.2</sub> /undoped ZnS multiple quantum wells. <i>Physical Review B</i> , 2003, 67, .	3.2	38
92	Efficient luminescence from Sm-doped ZnS <sub>Se</sub> /undoped-ZnS multi-quantum wells. <i>Journal of Crystal Growth</i> , 2000, 214-215, 935-938.	1.5	6
93	Quenching mechanism of luminescence in Sm-doped ZnS. <i>Journal of Crystal Growth</i> , 2000, 214-215, 954-957.	1.5	2
94	Compensation centers in ZnSeTe. <i>Journal of Applied Physics</i> , 1999, 86, 5993-5999.	2.5	5
95	Gold particles containing plasma-polymerized styrene as an X-ray absorber. <i>Plasma Chemistry and Plasma Processing</i> , 1987, 7, 155-167.	2.4	7
96	Compositional Dependence of Nonpolar <i>m</i> -Plane In <sub>x</sub> Ga <sub>1-x</sub> N/GaN Light Emitting Diodes. <i>Applied Physics Express</i> , 0, 1, 041101.	2.4	53